Product Change Notification

103777 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #:	**103777 - 00**
Change Title:	**Intel 8x11mm Stacked Chip Scale Package JEDEC Tray Transport Media Change, PCN 103777-00, FYI**
Date of Publication:	**December 23, 2003**

Type of Change Notification:

FYI - (For Your Information)

Key Characteristics of the Change:

Transport Media

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Dec 12, 2003
Date of First Availability of Post-Conversion Material:	Dec 12, 2003

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Intel ? Stacked Chip Scale Packages (SCSP) 8x11mm devices will be shipped in JEDEC Tray shipping media (if applicable) that has been modified to improve manufacturing robustness. The JEDEC Tray design will incorporate a Vacuum Fence design compared to the Non-Vacuum Fence design. The new tray design will adhere to JEDEC Design Standard for Chip Scale Packages (Generic Matrix Tray For Shipping and Handling, JEDEC Standard No-91-1 Nov. 1997 Revision C).

Customer Impact of Change and Recommended Action:

There will be no change to the package sizes or materials and the product will continue to meet Intel's stringent quality requirements.

Change to the JEDEC (shipping media): All critical dimensions on the JEDEC tray are the same with the addition of the vacuum fence. Device unit count will remain the same.

Customer's actions for the new JEDEC tray design are none to minimal. Dimensions on the new trays are identical on all key parameters, including pocket pitch, device orientation in the tray and the pocket seating depth. There are no anticipated required changes to the customer pick and place equipment.

`Product Code Numbers will not be changed for device line items impacted by this new tray.`

Products Affected / Intel Ordering Codes:

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#
JZ48F4000L0YBQ0856500	N/A	856500
JZ48F4000L0YBQ0Q T88	Q T88	856093
JZ48F4000L0YTQ0856502	N/A	856502
JZ48F4000L0ZBQ0857457	N/A	857457
JZ48F4000L0ZTQ0857464	N/A	857464
NZ48F4000L0YBQ0856503	N/A	856503
NZ48F4000L0YBQ0Q T87	Q T87	856096
NZ48F4000L0YTQ0856504	N/A	856504
NZ48F4000L0YTQ0Q T86	Q T86	856092
NZ48F4000L0ZBQ0857477	N/A	857477
NZ48F4000L0ZBQ0Q T84	Q T84	856090
NZ48F4000L0ZTQ0857478	N/A	857478
NZ48F4000L0ZTQ0Q T85	Q T85	856091
PF38F4050L0YBQ0Q U96	Q U96	857386
PF38F4050L0YTQ0Q U93	Q U93	857383
RD38F4050L0YBQ0Q U13	Q U13	855681
RD38F4050L0YTQ0Q U10	Q U10	855677
RD48F3300L0ZDQ0856548	N/A	856548
RD48F4040LVYBQ0Q U84	Q U84	857364
RD48F4040LVYTQ0Q U81	Q U81	857363
RD48F4040LVZBQ0Q U90	Q U90	857378
RD48F4040LVZTQ0Q U87	Q U87	857379
RD48F4400L0YDQ0854566	N/A	854566
RD48F4400L0YDQ0Q S15	Q S15	855366
RD48F4400L0YDQ0Q T25	Q T25	855474
RD48F4400L0ZDQ0855758	N/A	855758
RD48F4400L0ZDQ0Q S72	Q S72	855091
RD48F4400L0ZDQ0Q T28	Q T28	855477
RD58F0010LVZBQ0Q U53	Q U53	856567
RD58F0010LVZTQ0Q U50	Q U50	856564

Reference Documents / Attachments:

Document:	**Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
December 11, 2003	00	Originally Published PCN